

Ãœmit Bayram

List of Publications by Year in descending order

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Version: 2024-02-01

18

papers

78

citations

1683354

5

h-index

1473754

9

g-index

18

all docs

18

docs citations

18

times ranked

61

citing authors

#	ARTICLE	IF	CITATIONS
1	Investigations of Electrical Resistivity and Thermal Conductivity Dependences on Growth Rate in the Al-Cu-Ti Eutectic Alloy. <i>International Journal of Thermophysics</i> , 2021, 42, 1.	1.0	2
2	The variations of electrical resistivity and thermal conductivity with growth rate for the Zn-Al-Cu eutectic alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 18212-18223.	1.1	0
3	Effects of Growth Rate on Eutectic Spacing, Microhardness, and Ultimate Tensile Strength in the Al-Cu-Ti Eutectic Alloy. <i>Physics of Metals and Metallography</i> , 2020, 121, 382-390.	0.3	2
4	BI-IN SÄ°STEMÄ°NDE ELEKTRÄ°KSEL VE ISIL Ä°LETKENLÄ°K VE ISIL Ä°LETKENLÄ°ÄžE FONON KATKISI. <i>Isı Bilimi Ve Teknigi Dergisi/ Journal of Thermal Science and Technology</i> , 2020, 40, 367-378.	0.3	1
5	Effect of Sn contents on thermodynamic, microstructure and mechanical properties in the Zn90-Bi10 and Bi88-Zn12 based ternary alloys. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 3678-3691.	1.1	1
6	Thermal conductivity and electrical resistivity dependences on growth rate in the directionally solidified Al-Cu-Ni eutectic alloy. <i>Journal of Alloys and Compounds</i> , 2018, 753, 695-702.	2.8	16
7	Influence of Growth Rate on Eutectic Spacing, Microhardness, and Ultimate Tensile Strength in the Directionally Solidified Al-Cu-Ni Eutectic Alloy. <i>Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science</i> , 2018, 49, 3293-3305.	1.0	17
8	Solid-Liquid Interfacial Energy of Solid Succinonitrile in Equilibrium with Succinonitrile-(D)Camphor-Aminomethylpropanediol Eutectic Liquid. <i>International Journal of Thermophysics</i> , 2016, 37, 1.	1.0	0
9	Dependence of microstructural, mechanical and electrical properties on growth rates in directional solidified Zn-Al-Bi eutectic alloy. <i>Transactions of Nonferrous Metals Society of China</i> , 2016, 26, 2320-2335.	1.7	4
10	Dependence of microstructure, microhardness, tensile strength and electrical resistivity on growth rates for directionally solidified Zn-Al-Sb eutectic alloy. <i>International Journal of Materials Research</i> , 2016, 107, 1005-1015.	0.1	4
11	Thermal Conductivity of Solid Phases for Naphtol, Camphene, Salol, and Bezil. <i>Journal of Thermophysics and Heat Transfer</i> , 2016, 30, 730-736.	0.9	0
12	Solid-Liquid Interfacial Energy of Solid Neopentylglycol Solution in Equilibrium with Neopentylglycol-Aminomethylpropanediol Eutectic Liquid. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2013, 44, 4042-4050.	1.1	0
13	Measurements of Thermal Conductivity Variations with Temperature for the Organic Analog of the Nonmetal-Nonmetal System: Urea-4-Bromo-2-Nitroaniline. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2013, 44, 4051-4058.	1.1	0
14	Solid-liquid interfacial energy of neopentylglycol solid solution in equilibrium with succinonitrile-neopentylglycol-aminomethylpropanediol liquid. <i>Journal of Crystal Growth</i> , 2013, 364, 34-39.	0.7	2
15	Solid-liquid interfacial energy of solid aminomethylpropanediol solution in equilibrium with aminomethylpropanediol-(D) camphor liquid. <i>Thermochimica Acta</i> , 2013, 554, 48-53.	1.2	2
16	Thermal Conductivity Variation with Temperature for Lead-Free Ternary Eutectic Solders. <i>Journal of Electronic Materials</i> , 2013, 42, 3573-3581.	1.0	11
17	Solid-liquid interfacial energy of neopentylglycol solid solution in equilibrium with neopentylglycol-(D) camphor eutectic liquid. <i>Journal of Crystal Growth</i> , 2012, 338, 181-188.	0.7	7
18	Dependency of thermal conductivity on the temperature and composition of d-camphor in the neopentylglycol-d-camphor alloys. <i>Thermochimica Acta</i> , 2012, 531, 12-20.	1.2	9